

HEF4077B

Quad 2-input EXCLUSIVE-NOR gate

Rev. 4 — 18 July 2014

Product data sheet

1. General description

The HEF4077B is a quad 2-input EXCLUSIVE-NOR gate. The outputs are fully buffered for the highest noise immunity and pattern insensitivity to output impedance.

The HEF4077B operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD} , V_{SS} , or another input.

2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
HEF4077BP	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
HEF4077BT	$-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1

4. Functional diagram

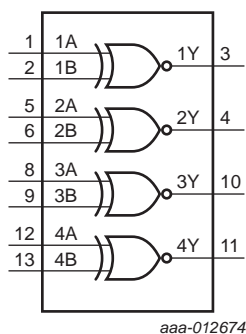


Fig 1. Functional diagram

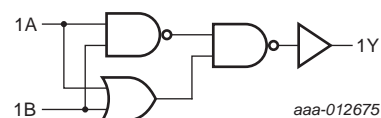


Fig 2. Logic diagram (one gate)



5. Pinning information

5.1 Pinning

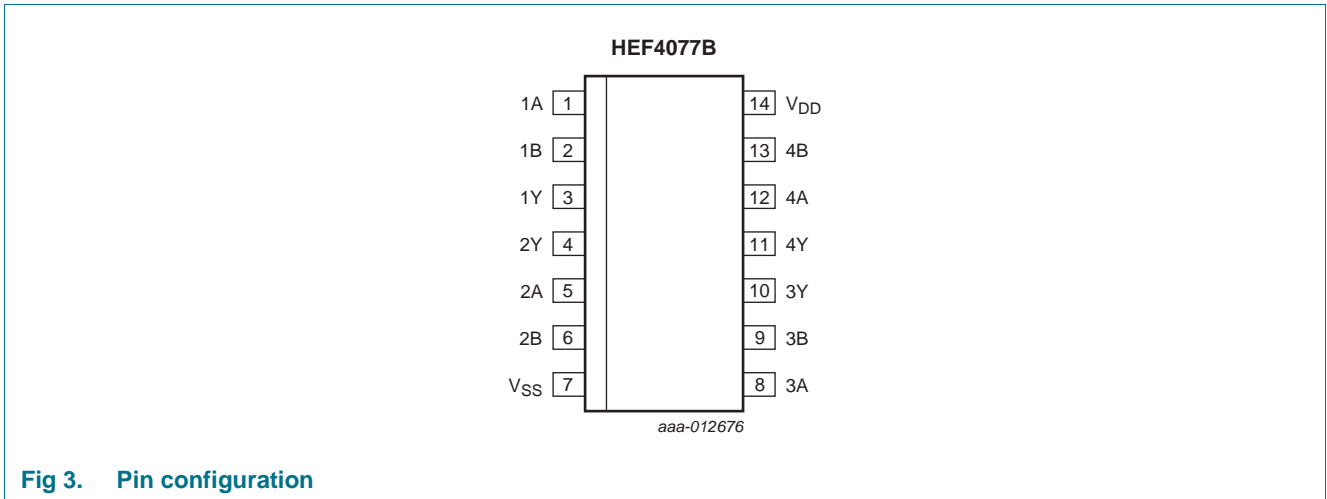


Fig 3. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A to 4A	1, 5, 8, 12	input
1B to 4B	2, 6, 9, 13	input
1Y to 4Y	3, 4, 10, 11	output
V _{SS}	7	ground (0 V)
V _{DD}	14	supply voltage

6. Functional description

Table 3. Functional table^[1]

Input		Output
nA	nB	nY
L	L	H
L	H	L
H	L	L
H	H	H

[1] H = HIGH voltage level; L = LOW voltage level.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to $V_{SS} = 0$ V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit	
V_{DD}	supply voltage		-0.5	+18	V	
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	± 10	mA	
V_I	input voltage		-0.5	$V_{DD} + 0.5$	V	
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{DD} + 0.5$ V	-	± 10	mA	
$I_{I/O}$	input/output current		-	± 10	mA	
I_{DD}	supply current		-	50	mA	
T_{stg}	storage temperature		-65	+150	°C	
T_{amb}	ambient temperature		-40	+85	°C	
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to + 85 °C				
		DIP14	[1]	-	750	mW
		SO14	[2]	-	500	mW
P	power dissipation	per output	-	100	mW	

[1] For DIP14 packages: above $T_{amb} = 70$ °C, P_{tot} derates linearly with 12 mW/K.

[2] For SO14 packages: above $T_{amb} = 70$ °C, P_{tot} derates linearly with 8 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		3	15	V
V_I	input voltage		0	V_{DD}	V
T_{amb}	ambient temperature	in free air	-40	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5$ V	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10$ V	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15$ V	-	0.08	$\mu\text{s/V}$

9. Static characteristics

Table 6. Static characteristics

$V_{SS} = 0\text{ V}$; $V_I = V_{SS}$ or V_{DD} ; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	$T_{amb} = -40\text{ °C}$		$T_{amb} = +25\text{ °C}$		$T_{amb} = +85\text{ °C}$		Unit
				Min	Max	Min	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
V_{IL}	LOW-level input voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V
V_{OH}	HIGH-level output voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
V_{OL}	LOW-level output voltage	$ I_O < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
I_{OH}	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	mA
		$V_O = 4.6\text{ V}$	5 V	-	-0.52	-	-0.44	-	-0.36	mA
		$V_O = 9.5\text{ V}$	10 V	-	-1.3	-	-1.1	-	-0.9	mA
		$V_O = 13.5\text{ V}$	15 V	-	-3.6	-	-3.0	-	-2.4	mA
I_{OL}	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.52	-	0.44	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.3	-	1.1	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	3.6	-	3.0	-	2.4	-	mA
I_I	input leakage current		15 V	-	± 0.3	-	± 0.3	-	± 3.0	μA
I_{DD}	supply current	all valid input combinations; $I_O = 0\text{ A}$	5 V	-	1.0	-	1.0	-	7.5	μA
			10 V	-	2.0	-	2.0	-	15.0	μA
			15 V	-	4.0	-	4.0	-	30.0	μA
C_I	input capacitance			-	-	-	7.5	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$; waveforms see [Figure 4](#); test circuit, see [Figure 5](#); unless otherwise specified. [1]

Symbol	Parameter	Conditions	V _{DD}	Extrapolation formula	Min	Typ	Max	Unit
t _{PHL}	HIGH to LOW propagation delay	nA or nB to nY	5 V	48 ns + (0.55 ns/pF)C _L	-	75	150	ns
			10 V	24 ns + (0.23 ns/pF)C _L	-	35	70	ns
			15 V	22 ns + (0.16 ns/pF)C _L	-	30	55	ns
t _{PLH}	LOW to HIGH propagation delay	nA or nB to nY	5 V	43 ns + (0.55 ns/pF)C _L	-	70	145	ns
			10 V	19 ns + (0.23 ns/pF)C _L	-	30	60	ns
			15 V	17 ns + (0.16 ns/pF)C _L	-	25	50	ns
t _t	transition time		5 V [2]	10 ns + (1.00 ns/pF)C _L	-	60	120	ns
			10 V	9 ns + (0.42 ns/pF)C _L	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C _L	-	20	40	ns

[1] The typical value of the propagation delay and output transition time can be calculated with the extrapolation formula (C_L in pF).

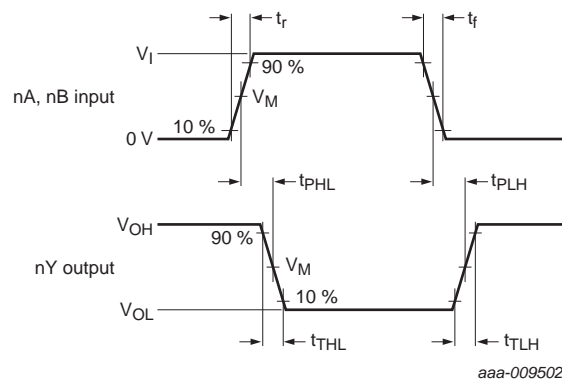
[2] t_t is the same as t_{THL} and t_{TLH}.

Table 8. Dynamic power dissipation

V_{SS} = 0 V; t_r = t_f ≤ 20 ns; T_{amb} = 25 °C.

Symbol	Parameter	V _{DD}	Typical formula	where:
P _D	dynamic power dissipation	5 V	P _D = 850 × f _i + Σ(f _o × C _L) × V _{DD} ² (μW)	f _i = input frequency in MHz;
		10 V	P _D = 4500 × f _i + Σ(f _o × C _L) × V _{DD} ² (μW)	f _o = output frequency in MHz;
		15 V	P _D = 114700 × f _i + Σ(f _o × C _L) × V _{DD} ² (μW)	C _L = output load capacitance in pF; Σ(f _o × C _L) = sum of the outputs; V _{DD} = supply voltage in V.

11. Waveforms



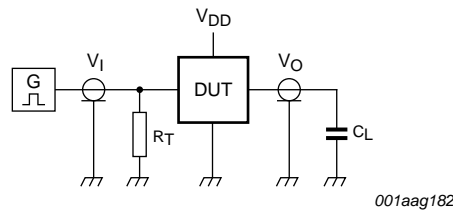
Measurement points are given in [Table 9](#).

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 4. Input to output propagation delay and output transition times

Table 9. Measurement points

Supply voltage	Input	Output
V_{DD}	V_M	V_M
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$



Test data is given in [Table 10](#).

Definitions for test circuit:

DUT = Device Under Test.

C_L = load capacitance including jig and probe capacitance.

R_T = termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig 5. Test circuit

Table 10. Test data

Supply voltage	Input	Load
V_{DD}	V_I	C_L
5 V to 15 V	V_{SS} or V_{DD}	t_r, t_f
		≤ 20 ns
		50 pF

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

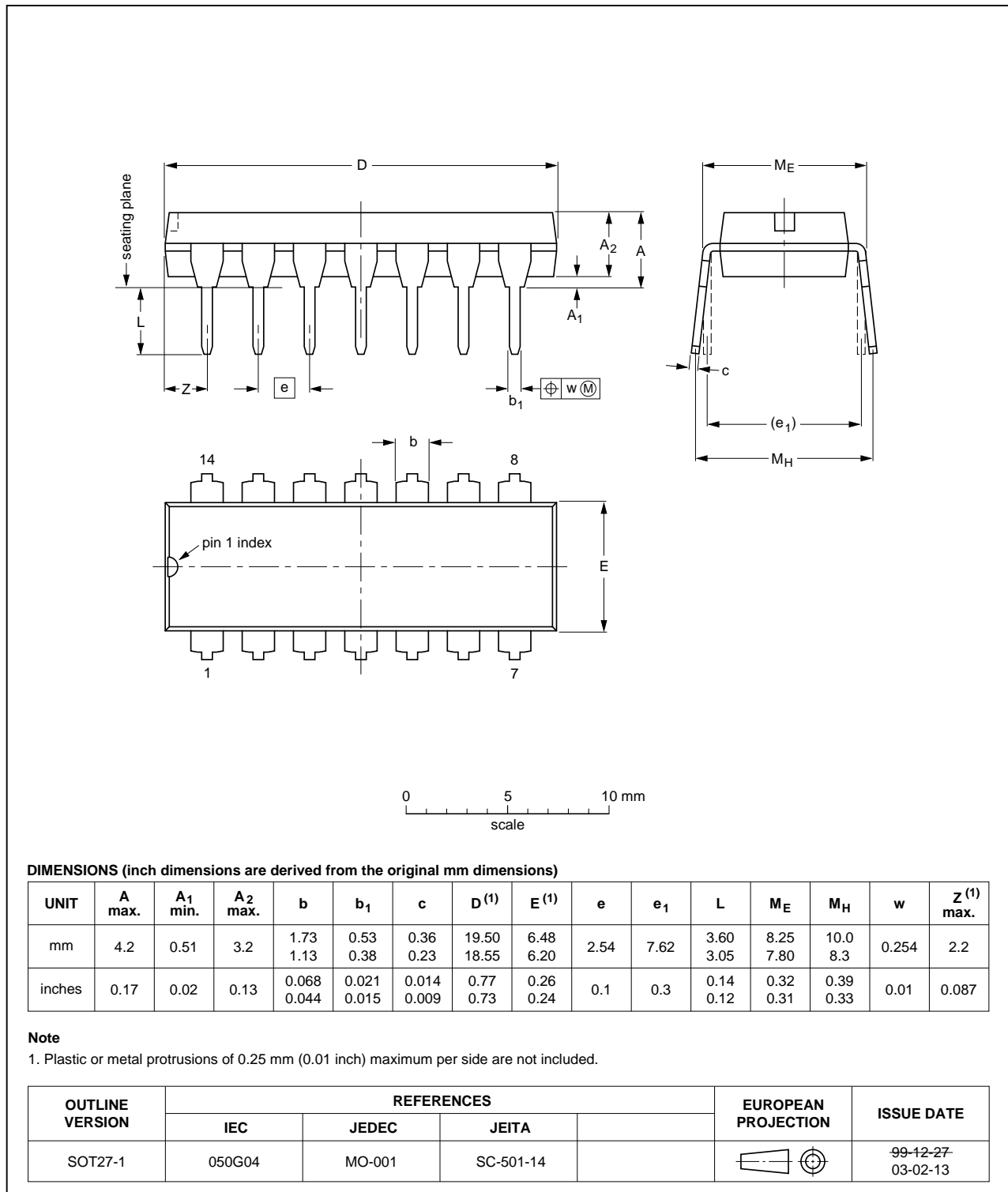


Fig 6. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

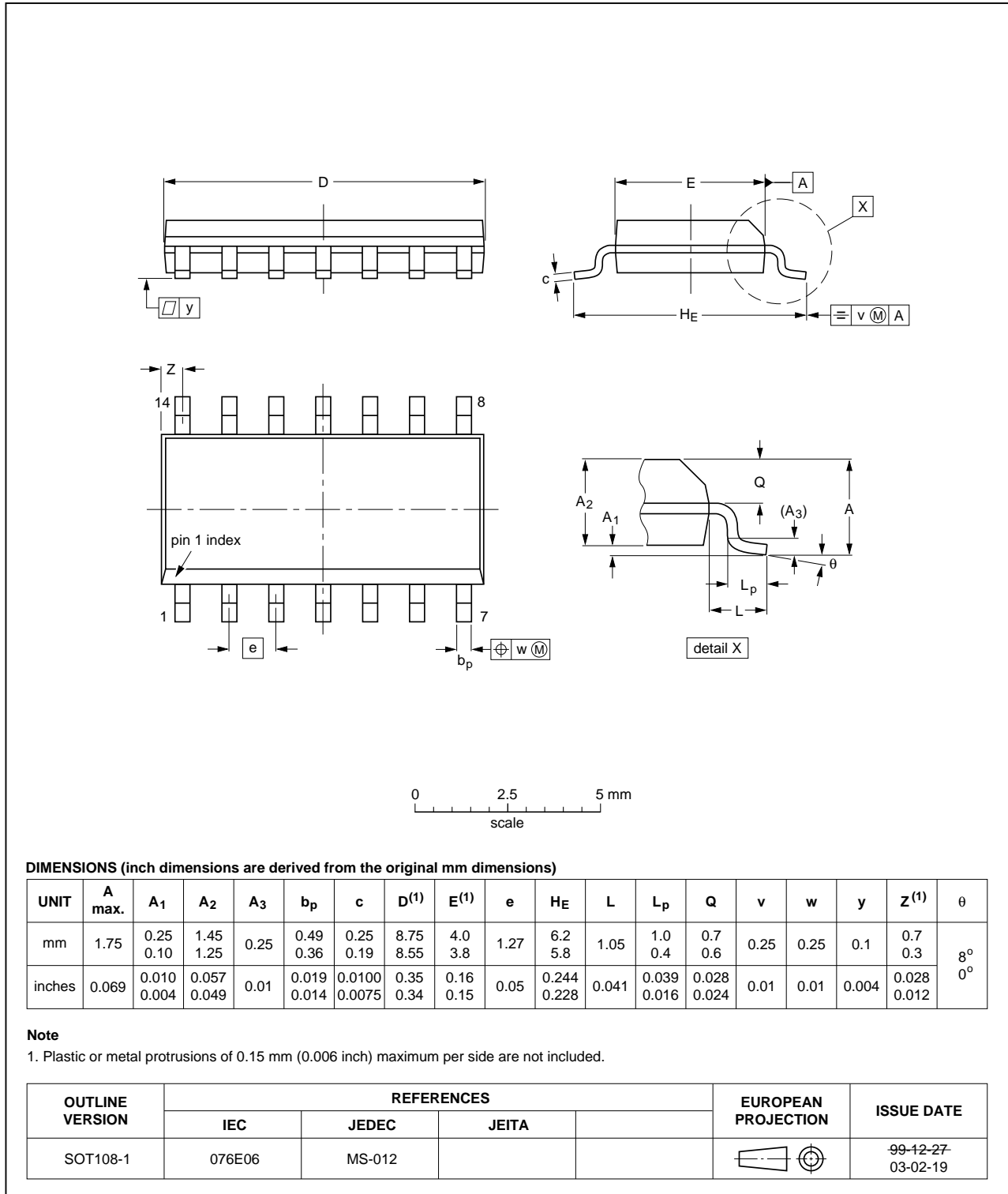


Fig 7. Package outline SOT108-1 (SO14)

13. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged-Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4077B v.4	20140718	Product data sheet	-	HEF4077B_CNV_3
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Data sheet is imported into latest template. 			
HEF4077B_CNV_3	19950101	Product specification	-	-

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Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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